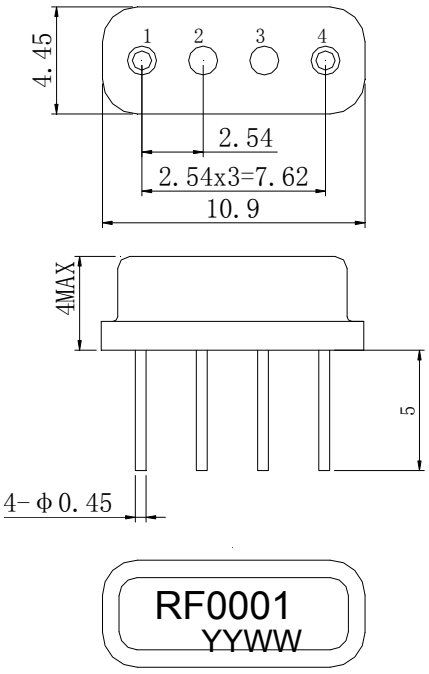
Application

- Low-loss SAW component
- Low amplitude ripple
- Sharp rejections at both out-bands
- Usable passband 320 kHz

Features

- **RoHS** compatible
- Package size 10.9x4.45x4.00mm^3
- Package Code SC04-06
- **E**lectrostatic **S**ensitive **D**evice(**ESD)**

Package Dimensions (Unit: mm)



Pin Configuration

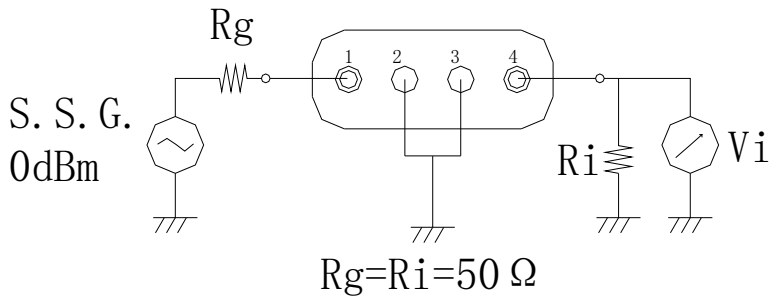
Pin No.	Description
1	Input
4	Output
2,3	Ground

Marking Description

R	Manufacturer
F	SAW Filter
0001	Part Number
YYWW	Year Code & Week Code

*Fig: If the products produced in 06th week of 2012, The year code & week code is 1206.

Test Circuit



Performance

Maximum Rating

Item		Value	Unit
DC Voltage	V_{DC}	3	V
Operation Temperature	T	-40 ~ +85	℃
Storage Temperature	T_{stg}	-55 ~ +125	℃
RF Power Dissipation	P	15	dBm

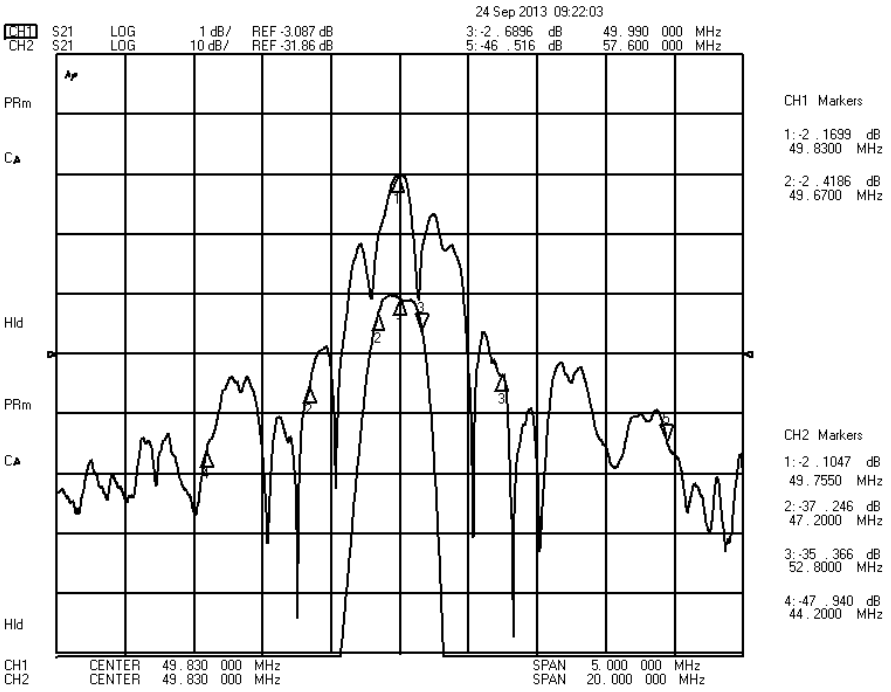
Electronic Characteristics

Test Temperature: 25℃±2℃
Terminating source impedance: 50Ω
Terminating load impedance: 50Ω

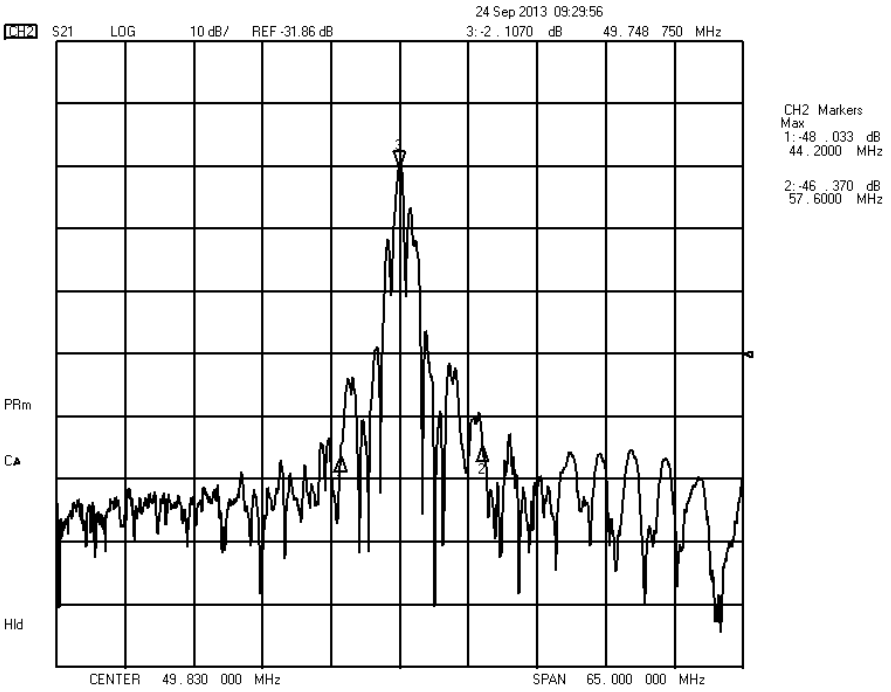
Item		Minimum	Typical	Maximum	Unit
Center Frequency	fc		49.83		MHz
Insertion Loss(min)	IL		2.1	2.7	dB
Insertion Loss 49.67 - 49.99 MHz	IL		2.5	4.0	dB
Amplitude Ripple (p-p) 49.67 - 49.99 MHz	△α		0.5	1.5	dB
3dB Bandwidth	BW_{3dB}		570	620	KHz
Absolute Attenuation	α				
DC-32.20 MHz		45	50		dB
32.20 - 43.40 MHz		40	42		dB
43.40 - 47.20 MHz		30	35		dB
55.30 - 57.60 MHz		30	35		dB
57.60 - 82.30 MHz		40	42		dB

Frequency Characteristics

Frequency Response



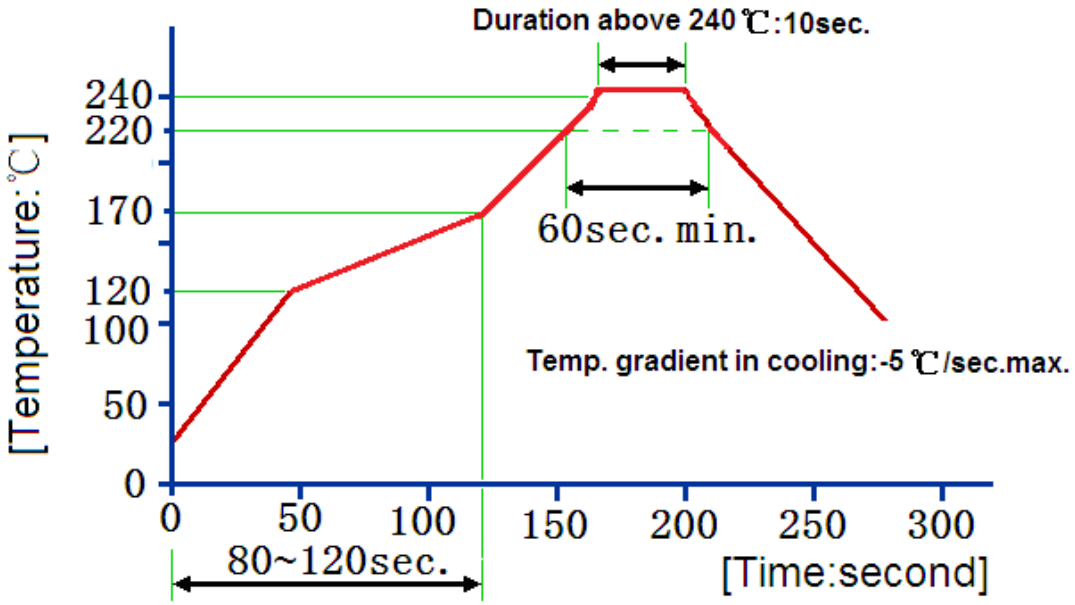
Frequency Response（wideband）



Reliability（The SAW components shall remain electrical performance after tests）

No.	Test item	Test condition
1	Temperature Storage	(1) Temperature: 85℃±2℃ , Duration: 250h , Recovery time: 2h±0.5h (2) Temperature: –55℃±3℃ , Duration: 250h ,Recovery time: 2h±0.5h
2	Humidity Test	Conditions: 60℃±2℃ , 90~95% RH Duration: 250h
3	Thermal Shock	Heat cycle conditions: TA=-55℃±3℃, TB=85℃±2℃, t1=t2=30min, Switch time: ≤3min, Cycle time: 100 times, Recovery time: 2h±0.5h.
4	Vibration Fatigue	Frequency of vibration: 10~55Hz Amplitude:1.5mm Directions: X,Y and Z Duration: 2h
5	Drop Test	Cycle time: 10 times Height: 1.0m
6	Solder Ability Test	Temperature: 245℃±5℃ Duration: 3.0s--5.0s Depth: DIP--2/3 , SMD--1/5
7	Resistance to Soldering Heat	(1)Thickness of PCB:1mm , Solder condition: 260℃±5℃ , Duration: 10±1s (2)Temperature of Soldering Iron: 350℃±10℃ , Duration: 3~4s , Recovery time : 2 ± 0.5h

Recommended Reflow Soldering Diagram



Reflow cycles:3 cycles max.

Notes

1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to **ESD protect** in the test.
2. **Static voltage** between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
3. **Ultrasonic cleaning** may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
4. Only leads of component may **be soldered**. Please avoid soldering another part of component.
5. There is a close relationship between the device's performance and **matching network**. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.